



## **R&D/LIMITED PRODUCTION CMP SYSTEMS**

- **4" – 12" Wafer Diameter Capacity**
- **Process up to two (2) wafers simultaneously or choose in-situ pad conditioning**
- **Compact, space-efficient systems**
- **True CMP processing without a CMP system price**
- **Can be used on Semiconductor, Compound Semiconductor (hard) and MEMS/NEMS substrate materials**
- **Fully programmable and independent kinematics for platen drive: Polishing head drives, polishing head pressure, polishing head oscillation & speed**
- **Operator's control touch-screen interface**
- **Menu-driven operations software**
- **Non-corrosive & low-expansion material construction**
- **Multi-Processing: Quick-change platen & polishing heads**



**Model 712 System**



**Model 612 System**

# LAPMASTER

## R&D/Limited Production CMP Systems

### EQUIPMENT SPECIFICATIONS

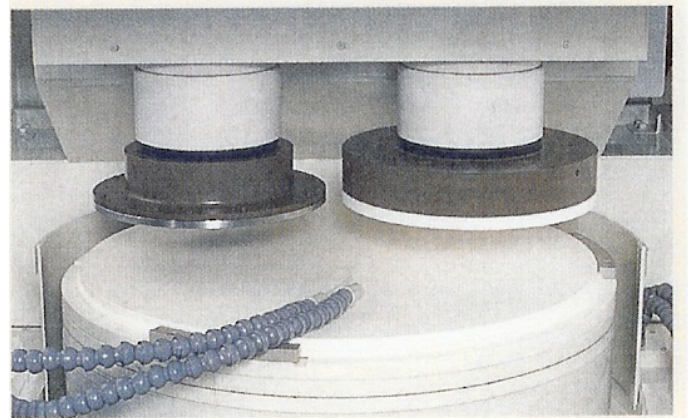
	Model 612	Model 712
Wafer Diameters	4-8"	8-12"
Platen Diameter	620mm (24")	680mm (27")
Platen RPM	20-120 RPM	20-120 RPM
Down-Force Range	20-250 pounds	40-525 pounds
Oscillation Stroke	0-60mm (2.4")	0-60mm (2.4")
Oscillation Speed	0-10 strokes/m	0-10 strokes/m
CMP Unit Width	47"	47"
CMP Unit Depth	47"	51"
CMP Unit Height	83"	90"
Work Stations	2	2
CNC Control	Standard	Standard
Variable Oscillation	Stroke & Speed	Stroke & Speed
3 Independent Spindle Drive	Standard	Standard
Al2O3 Ceramic Platen	Standard	Standard
Quick-Change Platen	Standard	Standard
Quick-Change Heads	Standard	Standard



**Model 612 Control Panel/Touch Screen**

### SYSTEM FEATURES

- 4"-8" or 8"-12" Wafer Diameter Capacity
- Fully independent kinematics (3 spindles)
- Multi-Axis drives with independent oscillation
- Quick-change platen and polish heads
- Menu-driven touch screen controls
- Process 2 wafers simultaneously or process 1 wafer at a time combined with in-situ pad conditioning
- Compliant construction for clean room environment
- Arranged to process semiconductor, compound semiconductor & MEMS/NEMS substrates
- Stable aluminum oxide ceramic platen
- Non-corrosive, low-expansion materials
- Accessible design for easy maintenance
- Excellent operator access and ergonomics
- Affordable and compact systems



**Model 712 Platen and Polishing Heads**



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